# **Small Signal MOSFET**

# 30 V, 270 mA, Single N-Channel, SC-70

#### **Features**

- Low Gate Charge for Fast Switching
- Small Footprint 30% Smaller than TSOP–6
- ESD Protected Gate
- Pb–Free Package for Green Manufacturing (G Suffix)

#### **Applications**

- Low Side Load Switch
- Li-Ion Battery Supplied Devices Cell Phones, PDAs, DSC
- Buck Converters
- Level Shifts

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter			Symbol	Value	Units
Drain-to-Source Voltage			$V_{DSS}$	30	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain Steady		T <sub>A</sub> = 25 °C	I <sub>D</sub>	270	mA
Current (Note 1)	State	T <sub>A</sub> = 85 °C		200	
Power Dissipation (Note 1)	Steady State	T <sub>A</sub> = 25 °C	P <sub>D</sub>	330	mW
Pulsed Drain Current t =10 μs			I <sub>DM</sub>	200	mA
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C
Source Current (Body Diode)			I <sub>S</sub>	270	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T <sub>L</sub>	260	°C

1. Surface mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [1 oz] including traces).

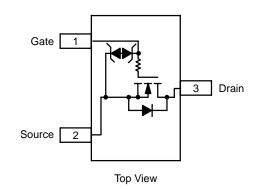


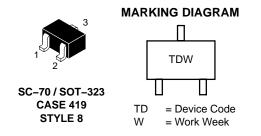
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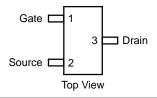
V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> Max
30 V	1.0 Ω @ 4.0 V	270 mA
	1.5 Ω @ 2.5 V	210 IIIA

#### SC-70 SOT-323 (3 LEADS)





#### **PIN ASSIGNMENT**



#### **ORDERING INFORMATION**

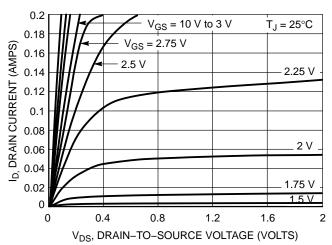
Device	Package	Shipping
NTS4001NT1	SC-70	3000 Units/Reel
NTS4001NT1G	SC-70 (Pb-Free)	3000 Units/Reel

#### **ELECTRICAL CHARACTERISTICS** (T<sub>1</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 100 \mu\text{A}$		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				60		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V				1.0	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$				±1.0	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{I}$	ο = 100 μΑ	0.8	1.2	1.5	V
Gate Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-3.4		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = 4.0 \text{ V},$	I <sub>D</sub> = 10 mA		1.0	1.5	Ω
		$V_{GS} = 2.5 \text{ V},$	I <sub>D</sub> = 10 mA		1.5	2.0	7
Forward Transconductance	9 <sub>FS</sub>	$V_{DS} = 3.0 \text{ V}, I_{D} = 10 \text{ mA}$			80		mS
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, } f = 1.0 \text{ MHz,}$ $V_{DS} = 5.0 \text{ V}$			20	33	pF
Output Capacitance	C <sub>OSS</sub>				19	32	
Reverse Transfer Capacitance	C <sub>RSS</sub>				7.25	12	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = 5.0 \text{ V}, V_{DS} = 24 \text{ V},$ $I_{D} = 0.1 \text{ A}$			0.9	1.3	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>				0.2		
Gate-to-Source Charge	Q <sub>GS</sub>				0.3		
Gate-to-Drain Charge	$Q_{GD}$				0.2		
SWITCHING CHARACTERISTICS (No	ote 3)						
Turn-On Delay Time	td <sub>(ON)</sub>	$V_{GS} = 4.5 \text{ V}, \text{ V}$ $I_D = 10 \text{ mA}, \text{ I}$	$I_{DD} = 5.0 \text{ V},$		17		ns
Rise Time	tr	$I_D$ = 10 mA, $R_G$ = 50 $\Omega$			23		
Turn-Off Delay Time	td <sub>(OFF)</sub>				94		
Fall Time	tf				82		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage			T <sub>J</sub> = 25°C		0.65	0.7	V
		$I_S = 10 \text{ mA}$	T <sub>J</sub> = 125°C		0.43		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 8.0 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ mA}$			5.0		ns

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

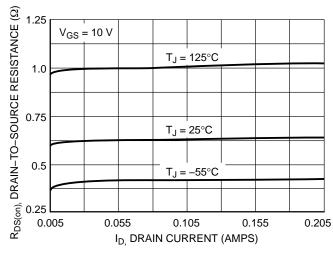
#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)



0.1 V<sub>DS</sub> = 5 V 0.08 V<sub>DS</sub> = 5 V T<sub>J</sub> = 125°C 1.2 1.4 1.6 1.8 2 2.2 V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



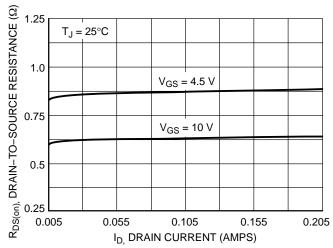
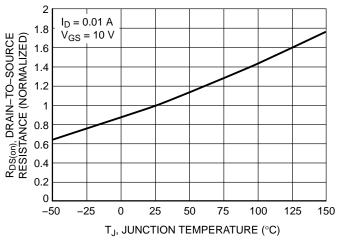


Figure 3. On–Resistance vs. Drain Current and Temperature

Figure 4. On–Resistance vs. Drain Current and Gate Voltage



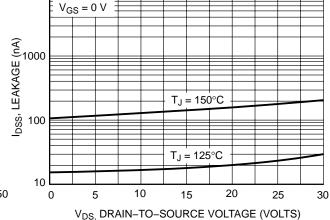
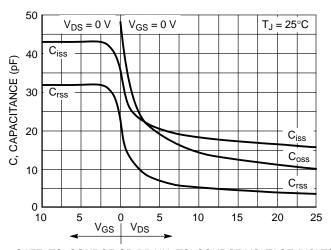


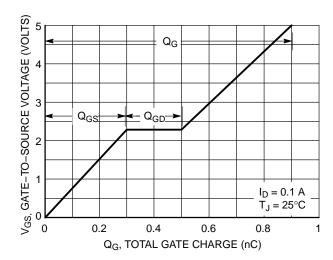
Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

10000

## TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)





GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

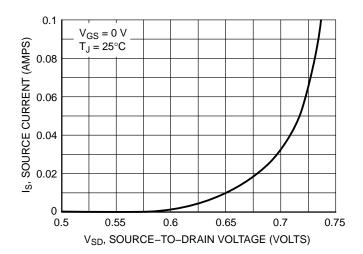
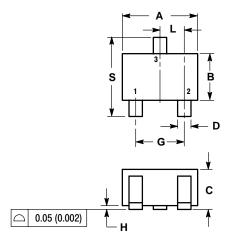
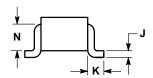


Figure 9. Diode Forward Voltage vs. Current

#### **PACKAGE DIMENSIONS**

**SC-70 (SOT-323)** CASE 419-04 ISSUE L





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.032	0.040	0.80	1.00	
D	0.012	0.016	0.30	0.40	
G	0.047	0.055	1.20	1.40	
Н	0.000	0.004	0.00	0.10	
۲	0.004	0.010	0.10	0.25	
K	0.017 REF		0.425	REF	
L	0.026 BSC		0.650 BSC		
N	0.028 REF		0.700 REF		
0	0.079	0.005	2.00	2.40	

STYLE 8: PIN 1. GATE 2. SOURCE 3. DRAIN

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